

ABSTRACT OF THE DISCLOSURE

The present invention provides a plating method and a plating apparatus capable of plating small parts effectively without any deformation. A object product to be plated is put in each accommodating concave portion 51 in a carrier tape 5 including a number of the accommodating concave portions 51, 51, 51 spaced at a specific interval and this carrier tape 5 is passed through a plating apparatus 2 so as to form metallic plating layer on the surface of the object product to be plated.